# FINEFLEX BIO™ Board

FINEFLEX BIO™ Board is a product made by adding organic and inorganic binders to FINEFLEX BIO™ Bulk and molding it into a board shape.

TOMBO™ No.5625-M is a low odor type to which small amounts of organic binder are added. TOMBO™ No.5625-A is a general-purpose type with excellent workability.

#### Features

- Exhibits an excellent thermal insulating effect due to its light weight and low thermal conductivity.
- Production of processed goods is possible.

## Applications

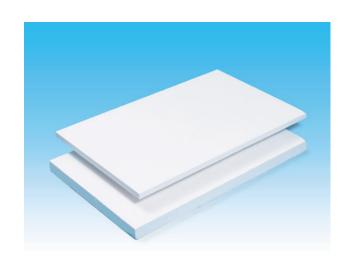
- Standard high-temperature insulating material
- Lining material and backup material for insulating ceilings and walls of kilns
- Expansion joint filling material for interior parts of kilns
- Gas seal material

## Quality Characteristics

Item		TOMBO™ No.		
		5625-M	5625-A	
Features		Low odor type	Excellent workability	
Color		White		
Density (kg/m³)		250		
Max. heatproof temp. (°C)		1300		
Normal usage temperature (°C)		1000		
Bending strength (MPa)	Normal state	0.2	0.5	
Coefficient of thermal contraction (%)	1000°C	1.2	0.9	
	1200°C	1.7	2.8	
Ignition loss (%)		0.7	4.0	
Chemical composition		SiO <sub>2</sub> , CaO, MgO, Other		

<sup>\*</sup> The above figures are actual measurements made by Nichias and not standard values.

Please inform us of your usage conditions when ordering.



## Standard Dimensions

Thickness (mm)	Width × length (mm)	
25	000 000	
50	600 × 900	

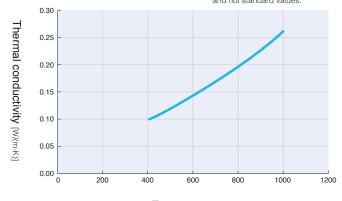
<sup>\*</sup> Please contact us for inquiries about other sizes.

## Packaging/Quantities

TOMBO™ No.	Carton dimensions (mm)	Quantity	
TOMBO NO.		Thickness 25mm	Thickness 50mm
5625-M	110 × 620 × 920	4	2
5625-A			

## Thermal conductivity

\* The following figures are actual measurements made by Nichias and not standard values.



Temperature (°C) Thermal conductivity of TOMBO No.5625-A/M

\* TOMBO is a registered trademark or trademark of Nichias Corporation.



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<sup>\*</sup> Depending on usage environment, deformation or cracking may occur at temperatures over 1100°C.

<sup>\*</sup> TM indicates a trademark of Nichias Corporation